

4 Pad Ceramic Package Quartz Crystal, 1.0 mm x 1.2 mm

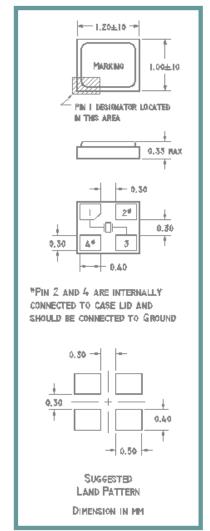
Product Features:

Low Cost SMD Package Ultra Miniature Package Compatible with Leadfree Processing

Applications:

Fibre Channel Server & Storage Sonet /SDH 802.11 / Wifi T1/E1, T3/E3 IOT

Frequency	36 MHz to 80 MHz (Contact Sales Representative for developed frequencies)		
ESR (Equivalent Series Resistance)			
36.0 MHz – 40.0 MHz 40.0 MHz – 48.0 MHz 48.0 MHz – 80.0 MHz	150 Ω Max. 80 Ω Max. 60 Ω Max.		
Shunt Capacitance (C0)	3.0 pF Max.		
Frequency Tolerance @ 25° C	±30 ppm Standard (see Part Number Guide for more options)		
Frequency Stability over Temperature	± 50 ppm Standard (see Part Number Guide for more options)		
Crystal Cut	AT Cut		
Load Capacitance	6 pF Standard		
Drive Level	100 μW Max.		
Aging	±3 ppm Max. / Year Standard		
Temperature			
Operating	-20° C to +70° C (see Part Number Guide for more options)		
Storage	-40° C to +85° C		



Part Number Guide	ber Guide Sample Part Number: ILCX21 - FB1F6 - 37.400					
Package	Tolerance (ppm) at Room Temperature	Stability (ppm) over Operating Temperature	Operating Temperature Range	Mode (overtone)	Load Capacitance (pF)	Frequency
	B = ±50 ppm	B = ±50 ppm	0 = 0°C to +50°C	∃ F = Fundamental '	6 pF Standard	- 37 400 MHz
	F = ±30 ppm	F = ±30 ppm**	1 = 0°C to +70°C			
ILCX21 -	G = ±25 ppm	G = ±25 ppm**	2 = -10°C to +60°C			
	H = ±20 ppm	H = ±20 ppm**	3 = -20°C to +70°C		Or Specify	
	I = ±15 ppm	I = ±15 ppm**	5 = -40°C to +85°C			
	J = ±10 ppm*	J = ±10 ppm**	9 = -10°C to +50°C			

Not available at all frequencies. ** Not available for all temperature ranges.

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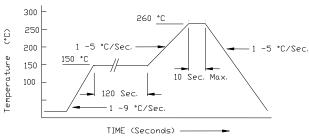




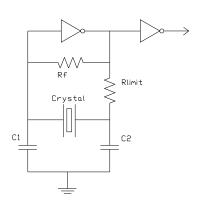
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Pb Free Solder Reflow Profile:

Typical Circuit:



^{*}Units are backward compatible with 240C reflow processes

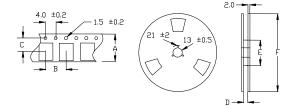


Package Information:

MSL = 1

Termination = e4 (Au over Ni over W base metal).

Tape and Reel Information:



Quantity per Reel	5000
Α	8 +/3
В	4 +/2
С	3.5 +/2
D	9 +/-1 or 12 +/-3
E	60 / 80
F	180

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Environmental Specifications

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

Marking

Line 1: I, Date Code (yww)

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